

REPETITIVE AVALANCHE AND dv/dt RATED HEXFET® TRANSISTOR

IRHNA7360SE

N-CHANNEL SINGLE EVENT EFFECT (SEE) RAD HARD

400 Volt, 0.20 Ω , (SEE) RAD HARD HEXFET

International Rectifier's (SEE) RAD HARD technology HEXFETs demonstrate virtual immunity to SEE failure. Additionally, under **identical** pre- and post-radiation test conditions, International Rectifier's RAD HARD HEXFETs retain **identical** electrical specifications up to 1×10^5 Rads (Si) total dose. No compensation in gate drive circuitry is required. These devices are also capable of surviving transient ionization pulses as high as 1×10^{12} Rads (Si)/Sec, and return to normal operation within a few microseconds. Since the SEE process utilizes International Rectifier's patented HEXFET technology, the user can expect the highest quality and reliability in the industry.

RAD HARD HEXFET transistors also feature all of the well-established advantages of MOSFETs, such as voltage control, very fast switching, ease of paralleling and temperature stability of the electrical parameters.

They are well-suited for applications such as switching power supplies, motor controls, inverters, choppers, audio amplifiers and high-energy pulse circuits in space and weapons environments.

Product Summary

Part Number	BV _{DSS}	R _{DS(on)}	I _D
IRHNA7360SE	400V	0.20 Ω	24.3A

Features:

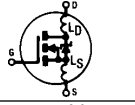
- Radiation Hardened up to 1×10^5 Rads (Si)
- Single Event Burnout (SEB) Hardened
- Single Event Gate Rupture (SEGR) Hardened
- Gamma Dot (Flash X-Ray) Hardened
- Neutron Tolerant
- Identical Pre- and Post-Electrical Test Conditions
- Repetitive Avalanche Rating
- Dynamic dv/dt Rating
- Simple Drive Requirements
- Ease of Paralleling
- Hermetically Sealed
- Surface Mount
- Lightweight

Absolute Maximum Ratings

Pre-Radiation

	Parameter	IRHNA7360SE	Units
I _D @ V _{GS} = 12V, T _C = 25°C	Continuous Drain Current	24.3	A
I _D @ V _{GS} = 12V, T _C = 100°C	Continuous Drain Current	15.3	
I _{DM}	Pulsed Drain Current ①	97.2	
P _D @ T _C = 25°C	Max. Power Dissipation	300	W
	Linear Derating Factor	2.4	W/K ⑤
V _{GS}	Gate-to-Source Voltage	±20	V
EAS	Single Pulse Avalanche Energy ②	500	mJ
I _{AR}	Avalanche Current ①	24.3	A
E _{AR}	Repetitive Avalanche Energy ①	30	mJ
dv/dt	Peak Diode Recovery dv/dt ③	4.0	V/ns
T _J	Operating Junction	-55 to 150	°C
T _{STG}	Storage Temperature Range		
	Package Mounting Surface Temperature	300 (for 5 sec.)	
	Weight	3.3 (typical)	g

Electrical Characteristics @ Tj = 25°C (Unless Otherwise Specified)

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
BV_{DSS}	Drain-to-Source Breakdown Voltage	400	—	—	V	$V_{GS} = 0V, I_D = 1.0 \text{ mA}$
$\Delta BV_{DSS}/\Delta T_J$	Temperature Coefficient of Breakdown Voltage	—	0.45	—	V/°C	Reference to 25°C, $I_D = 1.0 \text{ mA}$
RDS(on)	Static Drain-to-Source On-State Resistance	—	—	0.20	Ω	$V_{GS} = 12V, I_D = 15.3A$
		—	—	0.21		$V_{GS} = 12V, I_D = 24.3A$ ④
$V_{GS(th)}$	Gate Threshold Voltage	2.5	—	4.5	V	$V_{DS} = V_{GS}, I_D = 1.0 \text{ mA}$
g_{fs}	Forward Transconductance	4.75	—	—	S (r)	$V_{DS} > 15V, I_{DS} = 15.3A$ ④
IDSS	Zero Gate Voltage Drain Current	—	—	50	μA	$V_{DS} = 0.8 \times \text{Max Rating}, V_{GS} = 0V$
		—	—	250		$V_{DS} = 0.8 \times \text{Max Rating}, V_{GS} = 0V, T_J = 125^\circ C$
IGSS	Gate-to-Source Leakage Forward	—	—	100	nA	$V_{GS} = 20V$
IGSS	Gate-to-Source Leakage Reverse	—	—	-100	nA	$V_{GS} = -20V$
Qg	Total Gate Charge	—	—	180	nC	$V_{GS} = 12V, I_D = 24.3A$ $V_{DS} = \text{Max. Rating} \times 0.5$
Qgs	Gate-to-Source Charge	—	—	75		
Qgd	Gate-to-Drain ("Miller") Charge	—	—	100		
td(on)	Turn-On Delay Time	—	—	35	ns	$V_{DD} = 200V, I_D = 24.3A,$ $R_G = 2.35\Omega$
tr	Rise Time	—	—	100		
td(off)	Turn-Off Delay Time	—	—	100		
tf	Fall Time	—	—	100		
LD	Internal Drain Inductance	—	2.0	—	nH	<p>Measured from the drain lead, 6mm (0.25 in.) from package to center of die.</p> <p>Modified MOSFET symbol showing the internal inductances.</p> 
LS	Internal Source Inductance	—	6.5	—		
Ciss	Input Capacitance	—	7500	—	pF	$V_{GS} = 0V, V_{DS} = 25V$ $f = 1.0 \text{ MHz}$
Coss	Output Capacitance	—	1200	—		
Crss	Reverse Transfer Capacitance	—	500	—		

Source-Drain Diode Ratings and Characteristics

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
IS	Continuous Source Current (Body Diode)	—	—	24.3	A	Modified MOSFET symbol showing the integral reverse p-n junction rectifier.
ISM	Pulse Source Current (Body Diode) ①	—	—	97.2		
VSD	Diode Forward Voltage	—	—	1.4	V	$T_J = 25^\circ C, I_S = 24.3A, V_{GS} = 0V$ ④
trr	Reverse Recovery Time	—	—	750	ns	$T_J = 25^\circ C, I_F = 24.3A, di/dt \leq 100A/\mu s$ $V_{DD} \leq 50V$ ④
QRR	Reverse Recovery Charge	—	—	16	μC	
ton	Forward Turn-On Time	Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by LS + LD.				

Thermal Resistance

	Parameter	Min.	Typ.	Max.	Units	Test Conditions
RthJC	Junction-to-Case	—	—	0.42	K/W ⑤	Soldered to a copper-clad PC board
RthJ-PCB	Junction-to-PC Board	—	TBD	—		

Radiation Performance of Rad Hard HEXFETs

International Rectifier Radiation Hardened HEXFETs are tested to verify their hardness capability. The hardness assurance program at International Rectifier uses two radiation environments.

Every manufacturing lot is tested in a low dose rate (total dose) environment per MIL-STD-750, test method 1019. International Rectifier has imposed a standard gate voltage of 12 volts per note 6 and a V_{DS} bias condition equal to 80% of the device rated voltage per note 7. Pre- and post-radiation limits of the devices irradiated to 1×10^5 Rads (Si) are identical and are presented in Table 1, column 1, IRHNA7360SE. The values in Table 1 will be met for either of the two low dose rate test circuits that

are used. Both pre- and post-radiation performance are tested and specified using the same drive circuitry and test conditions in order to provide a direct comparison. It should be noted that at a radiation level of 1×10^5 Rads (Si), no change in limits are specified in DC parameters.

High dose rate testing may be done on a special request basis, using a dose rate up to 1×10^{12} Rads (Si)/Sec.

International Rectifier radiation hardened HEXFETs have been characterized in neutron and heavy ion Single Event Effects (SEE) environments. Single Event Effects characterization is shown in Table 3.

Table 1. Low Dose Rate ⑥ ⑦

Parameter		IRHNA7360SE		Units	Test Conditions ⑧
		100K Rads (Si)			
		min.	max.		
BV_{DSS}	Drain-to-Source Breakdown Voltage	400	—	V	$V_{GS} = 0V, I_D = 1.0 \text{ mA}$
$V_{GS(th)}$	Gate Threshold Voltage ④	2.0	4.5		$V_{GS} = V_{DS}, I_D = 1.0 \text{ mA}$
I_{GSS}	Gate-to-Source Leakage Forward	—	100	nA	$V_{GS} = 20V$
I_{GSS}	Gate-to-Source Leakage Reverse	—	-100		$V_{GS} = -20V$
I_{DSS}	Zero Gate Voltage Drain Current	—	50	μA	$V_{DS} = 0.8 \times \text{Max Rating}, V_{GS} = 0V$
$R_{DS(on)1}$	Static Drain-to-Source On-State Resistance One ④	—	0.20	Ω	$V_{GS} = 12V, I_D = 15.3A$
V_{SD}	Diode Forward Voltage ④	—	1.35	V	$T_C = 25^\circ C, I_S = 24.3A, V_{GS} = 0V$

Table 2. High Dose Rate ⑧

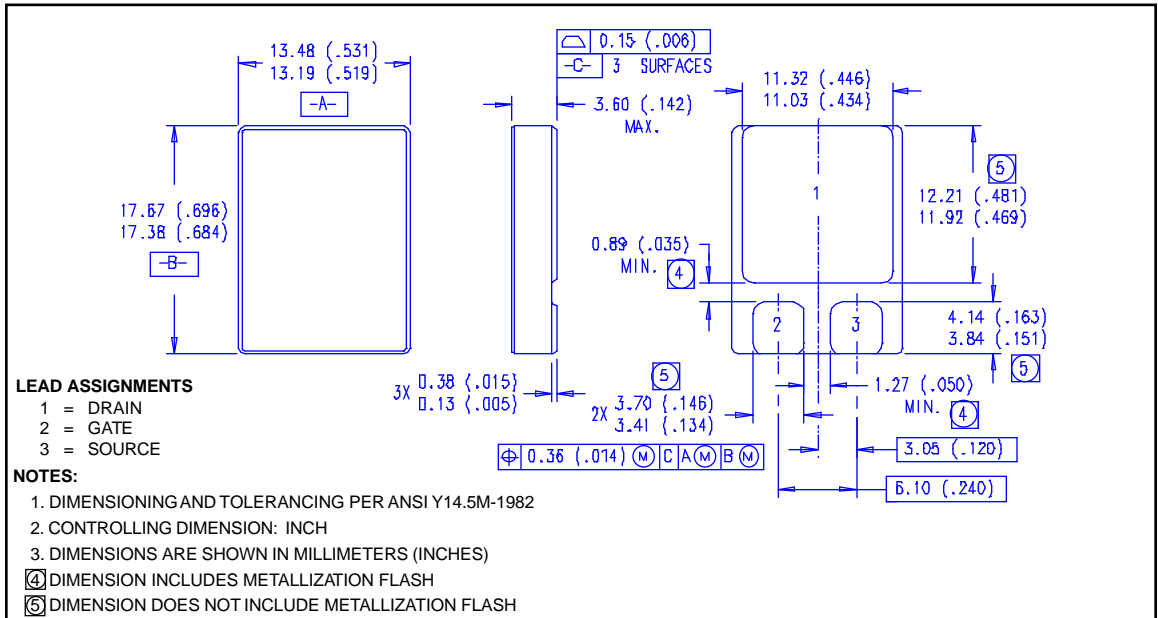
Parameter		10 ¹¹ Rads (Si)/sec			10 ¹² Rads (Si)/sec			Units	Test Conditions
		Min.	Typ.	Max.	Min.	Typ.	Max.		
V_{DSS}	Drain-to-Source Voltage	—	—	320	—	—	320	V	Applied drain-to-source voltage during gamma-dot
I_{PP}		—	6.4	—	—	6.4	—	A	Peak radiation induced photo-current
di/dt		—	—	16	—	—	2.3	A/ μ sec	Rate of rise of photo-current
L_1		20	—	—	137	—	—	μH	Circuit inductance required to limit di/dt

Table 3. Single Event Effects ⑨

Parameter	Typ.	Units	Ion	LET (Si) (MeV/mg/cm ²)	Fluence (ions/cm ²)	Range (μm)	V_{DS} Bias (V)	V_{GS} Bias (V)
BV_{DSS}	400	V	Ni	28	1×10^6	~35	320	-5

- ① Repetitive Rating; Pulse width limited by maximum junction temperature. Refer to current HEXFET reliability report.
- ② @ $V_{DD} = 50V$, Starting $T_J = 25^\circ C$,
 $E_{AS} = [0.5 * L * (I_L^2) * [BV_{DSS}/(BV_{DSS}-V_{DD})]]$
 Peak $I_L = 24.3A$, $V_{GS} = 12V$, $25 \leq R_G \leq 200\Omega$
- ③ $I_{SD} \leq 24.3A$, $di/dt \leq 170 A/\mu s$,
 $V_{DD} \leq BV_{DSS}$, $T_J \leq 150^\circ C$
 Suggested $R_G = 2.35\Omega$
- ④ Pulse width $\leq 300 \mu s$; Duty Cycle $\leq 2\%$
- ⑤ $K/W = ^\circ C/W$
 $W/K = W/^\circ C$
- ⑥ **Total Dose Irradiation with V_{GS} Bias.**
 12 volt V_{GS} applied and $V_{DS} = 0$ during irradiation per MIL-STD-750, method 1019.
- ⑦ **Total Dose Irradiation with V_{DS} Bias.**
 $V_{DS} = 0.8$ rated BV_{DSS} (pre-radiation) applied and $V_{GS} = 0$ during irradiation per MIL-STD-750, method 1019.
- ⑧ This test is performed using a flash x-ray source operated in the e-beam mode (energy ~ 2.5 MeV), 30 nsec pulse.
- ⑨ Process characterized by independent laboratory.
- ⑩ All Pre-Radiation and Post-Radiation test conditions are **identical** to facilitate direct comparison for circuit applications.

Case Outline and Dimensions - SMD2



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